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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/901,837	07/10/2001	Shubneesh Batra	MCRO:1993/FLE 95-0057.0	9030
75	90 03/24/2003			
Michael G. Fletcher EXAMINER			INER	
Fletcher, Yoder & Van Someren P.O. Box 692289 Houston, TX 77269-2289		EVERHART, CARIDAD		
			ART UNIT	PAPER NUMBER
			2825	
		DATE MAILED 02/04/0002		

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)
	DATRA ET AL	
Advisory Action	09/901,837	Art Unit
	Examiner  Covided M. Everhart	2825
	Caridad M. Everhart	
THE REPLY FILED 12 March 2003 FAILS TO PLACE Therefore, further action by the applicant is required to final rejection under 37 CFR 1.113 may only be either condition for allowance; (2) a timely filed Notice of Applicance with 37 CFR 1.114.	E THIS APPLICATION IN CON avoid abandonment of this ap (1) a timely filed amendment peal (with appeal fee); or (3) a	DITION FOR ALLOWANCE.  Oplication. A proper reply to a
Evamination (RCE) In COMPHANCE With 57 51 15 111 11	REPLY [check either a) or b)]	
	July of the final rejection	
a) The period for reply expiresmonths from the mailing by The period for reply expires on: (1) the mailing date of this event, however, will the statutory period for reply expire late ONLY CHECK THIS BOX WHEN THE FIRST REPLY W 706.07(f).  Extensions of time may be obtained under 37 CFR 1.136(a). The have been filed is the date for purposes of determining the period of exports of the shorts (b) above, if checked. Any reply received by the Office later than three earned patent term adjustment. See 37 CFR 1.704(b).	Advisory Action, or (2) the date set forth or than SIX MONTHS from the mailing deal (AS FILED WITHIN TWO MONTHS Of the date on which the petition under 37 CF oxtension and the corresponding amount amount the corresponding amount the correspo	THE FINAL REJECTION. See MPEP  R 1.136(a) and the appropriate extension fee of the fee. The appropriate extension fee under the final Office action; or (2) as set forth
1. A Notice of Appeal was filed on Appells 37 CFR 1.192(a), or any extension thereof (37	CFR 1.191(d)), to avoid distri-	the period set forth in ssal of the appeal.
The proposed amendment(s) will not be entere	ed because:	
(a) they raise new issues that would require for	urther consideration and/or sea	rch (see NOTE below);
	nta helΩW).	
(c) they are not deemed to place the applicat	ion in better form for appear by	
(d) they present additional claims without ca	nceling a corresponding numb	er of finally rejected claims.
3 Applicant's reply has overcome the following r	rejection(s):	
4. Newly proposed or amended claim(s) w	ould be allowable if submitted	
5. The a) affidavit, b) exhibit, or c) reque	C. COO COMMITTEE	
6. The affidavit or exhibit will NOT be considere	d because it is not directed SC	
7. For purposes of Appeal, the proposed amend explanation of how the new or amended claim	imant(c) a)    will not be entere	ed or b) will be entered and an ed below or appended.
The status of the claim(s) is (or will be) as fol		
Claim(s) allowed: Claim(s) objected to: Claim(s) rejected: <u>1 and 30-65</u> .		
Claim(s) withdrawn from consideration:  8.  The proposed drawing correction filed on	is a) approved or b)	disapproved by the Examiner.
9. Note the attached Information Disclosure Sta	atement(s)( P1O-1449) Paper	NU(3)
10. Other:		







Continuation of 5. does NOT place the application in condition for allowance because: Applicant has argued that in the final rejection, the Joshi reference was misinterpreted and that Joshi does not disclose the limitations added by applicant's amendment filed 10-21-02. This argument is respectfully disagreed with because a conductor layer can comprise more than one layer, so that the Al-Cu layer is a portion of the conductor layer, GeH4 gas is flowed, and an impurity layer is then formed and reflowed (col. 7, lines 28-34 and col. 8, lines 1-6). In another embodiment, the Al-Cu is formed, GeH4 is flowed, and the W material is formed and the layers are reflowed(col. 8, lines 40-51) . The Al-Cu portion is the portion of the conductive layer which is deposited before the impurity layer is formed, and the W material is the further portion of the conductive layer which is deposited, which reads applicant's claims. The impurity layer which is formed comprises Ge and Al-Cu-Ge. ..